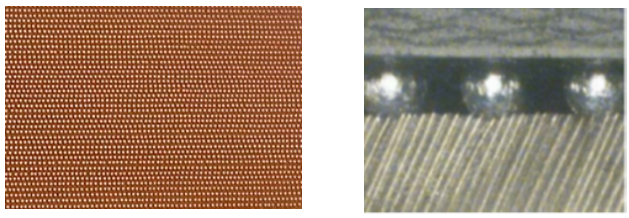
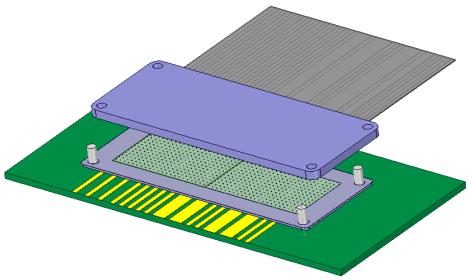
REDStrip interconnect

STEERED Technology

Goldwire-Elastomer interconnection technology



Application example BGA to PCB (above) and Board to Board (below)



QUICK FACTS

- Goldplated copper alloy contact element embedded in elastomer substrate.
- Contacts in matrix of 0,3 x 0,3 mm.
- Height between starting from 0.15 mm.
- Substrate size 3x3 to 50x50 mm
- Current carrying capability 50 mA per wire.
- Operating temperature -40 to +120 C.-
- Contact resistance 20 milliohm.
- Inseriton loss -1 dB @ 90Ghz.

PRODUCT APPLICATION

- All type of board to board, flex to board ,sensor or device to board both for dynamic as well as static applications in:

  - Semi-conductors
  - Test & Measurement
  - Medical
  - Aerospace
  - Defense-

FEATURES AND BENEFITS

- Small pitch and low height allows compact design.
- Electrically invisible allowing high data rates.
- Versatile, can use PCB, FEC, FPC.....
- Contacts ITO on Glass, semi-conductor material and coated foils.
- High number of mating cycles allows use in demanding applications
- Field replaceable keeps maintenance cost low.
- Dense wire grid allows programming interconnection to your needs.

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